

In case the packaging brings additional protection and shielding to the 3S included in the SoC (e.g. countermeasure like metal mesh sensor), and the final packaging is assembled after delivery (by an OEM for example) and/or after pre-personalization, the following policy and assumption must be added:

`P.Packaging_protection`: packaging design specifications must be provided by the 3S developer to the packaging manufacturer.

The 3S developer must provide packaging design specifications to the packaging manufacturer; the specification description must ensure that the final packaging will bring additional protections and shielding to the 3S included in the SoC.

`A.Packaging_protection`: packaging design specifications must be provided by the 3S developer to the packaging manufacturer

It is assumed that the packaging manufacturer has correctly followed the packaging design specifications provided by the 3S developer so the final packaging brings the expected additional protections and shielding to the 3S in SoC.

Application Note: In this context, the final packaging must be described in the life cycle section of the Security Target. Additionally, external DDR may be added after delivery of the TOE (e.g. using a Package-on-Package or other forms of manufacturing integration mechanisms), after the TOE has been personalized, up to delivery of the device including the TOE. In such case, External DDR assembly and integration processes must also be described in the life-cycle section of the Security Target.